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PSMN8R0-30YLC

N-channel 30 V 7.9 mΩ logic level MOSFET in LPAK using NextPower technology

Rev. 2 — 1 September 2011

Product data sheet

1. Product profile

1.1 General description

Logic level enhancement mode N-channel MOSFET in LPAK package. This product is designed and qualified for use in a wide range of industrial, communications and domestic equipment.

1.2 Features and benefits

- High reliability Power SO8 package, qualified to 175°C
- Low parasitic inductance and resistance
- Optimised for 4.5V Gate drive utilising NextPower Superjunction technology
- Ultra low QG, QGD, QOSS for high system efficiencies at low and high loads

1.3 Applications

- DC-to-DC converters
- Load switching
- Synchronous buck regulator

1.4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{DS}	drain-source voltage	$25\text{ °C} \leq T_j \leq 175\text{ °C}$	-	-	30	V
I_D	drain current	$T_{mb} = 25\text{ °C}; V_{GS} = 10\text{ V};$ see Figure 1	-	-	54	A
P_{tot}	total power dissipation	$T_{mb} = 25\text{ °C};$ see Figure 2	-	-	42	W
T_j	junction temperature		-55	-	175	°C
Static characteristics						
R_{DSon}	drain-source on-state resistance	$V_{GS} = 4.5\text{ V}; I_D = 15\text{ A};$ $T_j = 25\text{ °C};$ see Figure 12	-	8.5	10	mΩ
		$V_{GS} = 10\text{ V}; I_D = 15\text{ A};$ $T_j = 25\text{ °C};$ see Figure 12	-	6.7	7.9	mΩ

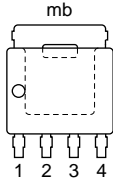
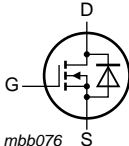


Table 1. Quick reference data ...continued

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Dynamic characteristics						
Q_{GD}	gate-drain charge	$V_{GS} = 4.5\text{ V}; I_D = 15\text{ A};$ $V_{DS} = 15\text{ V};$ see Figure 14 ; see Figure 15	-	2.3	-	nC
$Q_{G(tot)}$	total gate charge	$V_{GS} = 4.5\text{ V}; I_D = 15\text{ A};$ $V_{DS} = 15\text{ V};$ see Figure 14 ; see Figure 15	-	7	-	nC

2. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	S	source	 <p>SOT669 (LPAK; Power-SO8)</p>	 <p>mbb076</p>
2	S	source		
3	S	source		
4	G	gate		
mb	D	mounting base; connected to drain		

3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PSMN8R0-30YLC	LPAK; Power-SO8	plastic single-ended surface-mounted package; 4 leads	SOT669

4. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V _{DS}	drain-source voltage	25 °C ≤ T _j ≤ 175 °C	-	30	V
V _{DGR}	drain-gate voltage	25 °C ≤ T _j ≤ 175 °C; R _{GS} = 20 kΩ	-	30	V
V _{GS}	gate-source voltage		-20	20	V
I _D	drain current	V _{GS} = 10 V; T _{mb} = 25 °C; see Figure 1	-	54	A
		V _{GS} = 10 V; T _{mb} = 100 °C; see Figure 1	-	38	A
I _{DM}	peak drain current	pulsed; t _p ≤ 10 μs; T _{mb} = 25 °C; see Figure 4	-	216	A
P _{tot}	total power dissipation	T _{mb} = 25 °C; see Figure 2	-	42	W
T _{stg}	storage temperature		-55	175	°C
T _j	junction temperature		-55	175	°C
T _{sld(M)}	peak soldering temperature		-	260	°C
V _{ESD}	electrostatic discharge voltage	MM (JEDEC JESD22-A115)	190	-	V
Source-drain diode					
I _S	source current	T _{mb} = 25 °C	-	38	A
I _{SM}	peak source current	pulsed; t _p ≤ 10 μs; T _{mb} = 25 °C	-	216	A
Avalanche ruggedness					
E _{DS(AL)S}	non-repetitive drain-source avalanche energy	V _{GS} = 10 V; T _{j(init)} = 25 °C; I _D = 54 A; V _{sup} ≤ 30 V; R _{GS} = 50 Ω; unclamped; see Figure 3	-	12	mJ

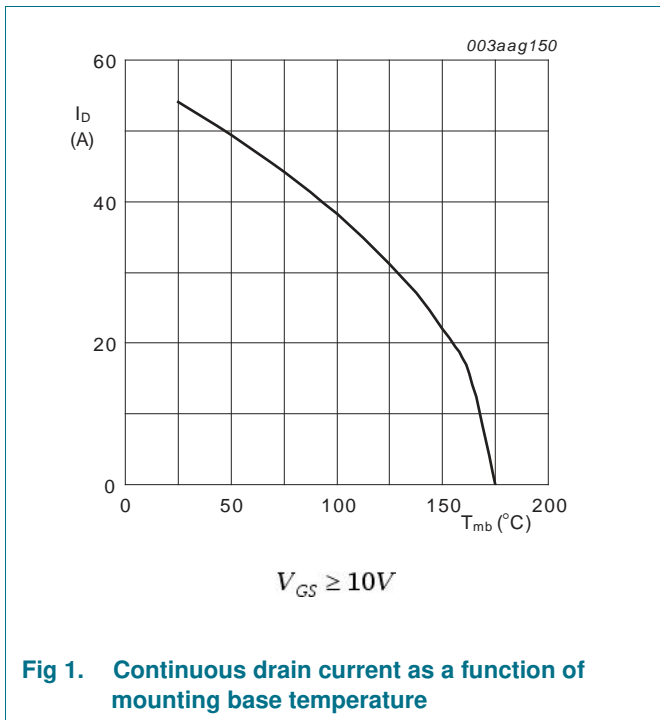


Fig 1. Continuous drain current as a function of mounting base temperature

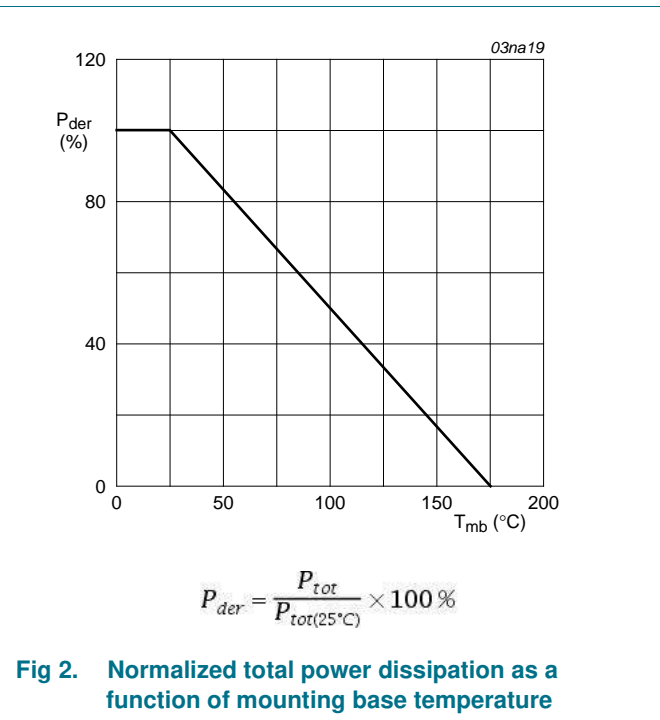


Fig 2. Normalized total power dissipation as a function of mounting base temperature

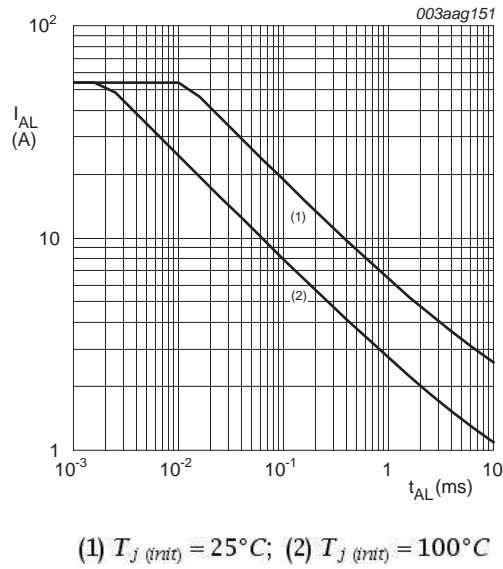


Fig 3. Single pulse avalanche rating; avalanche current as a function of avalanche time

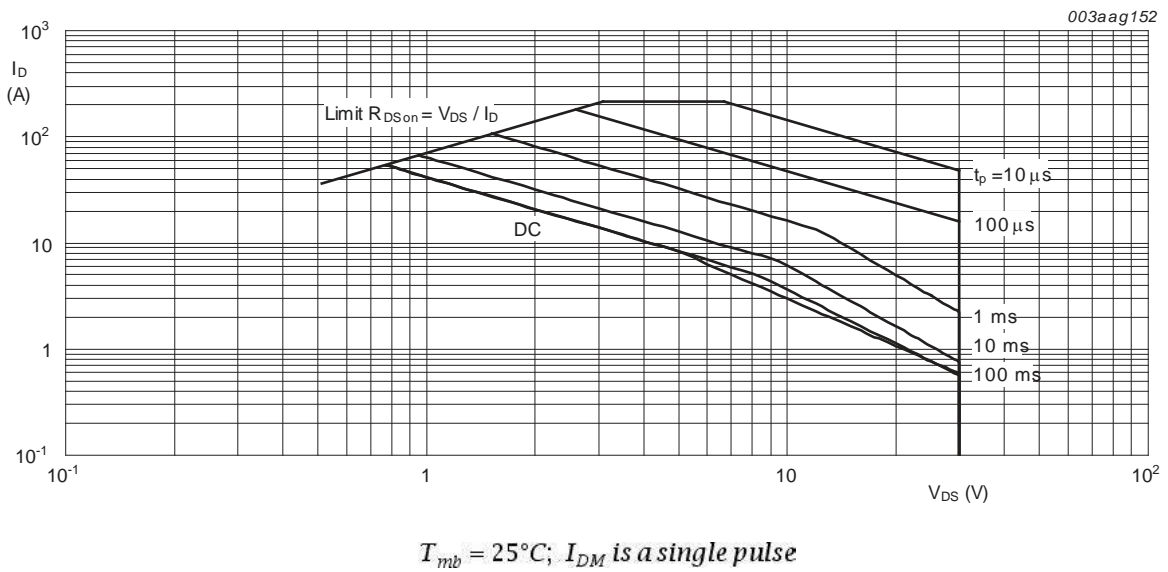


Fig 4. Safe operating area; continuous and peak drain currents as a function of drain-source voltage

5. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	see Figure 5	-	3.38	3.61	K/W

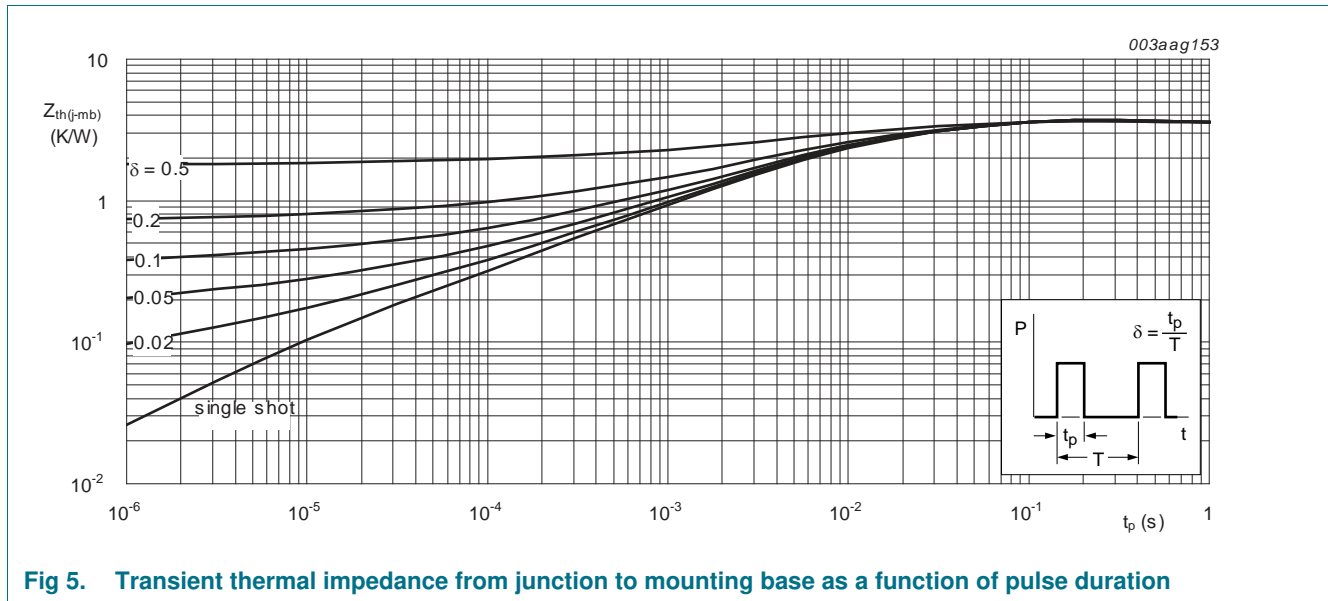


Fig 5. Transient thermal impedance from junction to mounting base as a function of pulse duration

6. Characteristics

Table 6. Characteristics

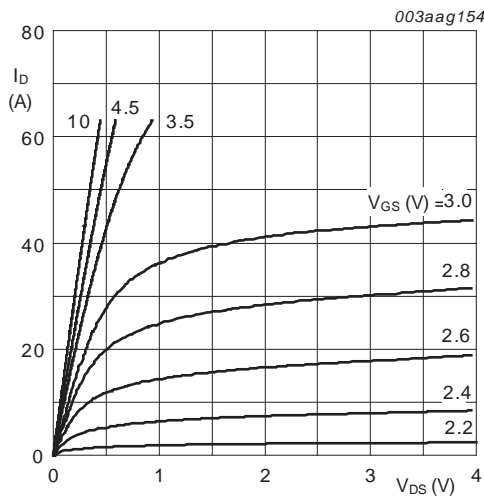
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
$V_{(BR)DSS}$	drain-source breakdown voltage	$I_D = 250 \mu A; V_{GS} = 0 V; T_j = 25 \text{ }^\circ C$	30	-	-	V
		$I_D = 250 \mu A; V_{GS} = 0 V; T_j = -55 \text{ }^\circ C$	27	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	$I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = 25 \text{ }^\circ C$; see Figure 10	1.05	1.59	1.95	V
		$I_D = 10 \text{ mA}; V_{DS} = V_{GS}; T_j = 150 \text{ }^\circ C$; see Figure 11	0.5	-	-	V
		$I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = -55 \text{ }^\circ C$; see Figure 11	-	-	2.25	V
I_{DSS}	drain leakage current	$V_{DS} = 30 V; V_{GS} = 0 V; T_j = 25 \text{ }^\circ C$	-	-	1	μA
		$V_{DS} = 30 V; V_{GS} = 0 V; T_j = 150 \text{ }^\circ C$	-	-	100	μA
I_{GSS}	gate leakage current	$V_{GS} = 16 V; V_{DS} = 0 V; T_j = 25 \text{ }^\circ C$	-	-	100	nA
		$V_{GS} = -16 V; V_{DS} = 0 V; T_j = 25 \text{ }^\circ C$	-	-	100	nA
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = 4.5 V; I_D = 15 A; T_j = 25 \text{ }^\circ C$; see Figure 12	-	8.5	10	mΩ
		$V_{GS} = 4.5 V; I_D = 15 A; T_j = 150 \text{ }^\circ C$; see Figure 12 ; see Figure 13	-	-	16.6	mΩ
		$V_{GS} = 10 V; I_D = 15 A; T_j = 25 \text{ }^\circ C$; see Figure 12	-	6.7	7.9	mΩ
		$V_{GS} = 10 V; I_D = 15 A; T_j = 150 \text{ }^\circ C$; see Figure 12 ; see Figure 13	-	-	13.2	mΩ
R_G	gate resistance	$f = 1 \text{ MHz}$	-	2.2	4.4	Ω
Dynamic characteristics						
$Q_{G(tot)}$	total gate charge	$I_D = 15 A; V_{DS} = 15 V; V_{GS} = 10 V$; see Figure 14 ; see Figure 15	-	15	-	nC
		$I_D = 15 A; V_{DS} = 15 V; V_{GS} = 4.5 V$; see Figure 14 ; see Figure 15	-	7	-	nC
		$I_D = 0 A; V_{DS} = 0 V; V_{GS} = 10 V$	-	13	-	nC
Q_{GS}	gate-source charge	$I_D = 15 A; V_{DS} = 15 V; V_{GS} = 4.5 V$; see Figure 14 ; see Figure 15	-	2.1	-	nC
$Q_{GS(th)}$	pre-threshold gate-source charge		-	1.5	-	nC
$Q_{GS(th-pl)}$	post-threshold gate-source charge		-	0.6	-	nC
Q_{GD}	gate-drain charge		-	2.3	-	nC
$V_{GS(pl)}$	gate-source plateau voltage	$I_D = 15 A; V_{DS} = 15 V$; see Figure 14 ; see Figure 15	-	2.6	-	V
C_{iss}	input capacitance	$V_{DS} = 15 V; V_{GS} = 0 V; f = 1 \text{ MHz}$;	-	848	-	pF
C_{oss}	output capacitance	$T_j = 25 \text{ }^\circ C$; see Figure 16	-	207	-	pF
C_{rss}	reverse transfer capacitance		-	70	-	pF

Table 6. Characteristics ...continued

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$t_{d(on)}$	turn-on delay time	$V_{DS} = 15\text{ V}; R_L = 1\ \Omega; V_{GS} = 4.5\text{ V};$	-	15	-	ns
t_r	rise time	$R_{G(ext)} = 4.7\ \Omega$	-	11	-	ns
$t_{d(off)}$	turn-off delay time		-	19	-	ns
t_f	fall time		-	7	-	ns
Q_{oss}	output charge	$V_{GS} = 0\text{ V}; V_{DS} = 15\text{ V}; f = 1\text{ MHz};$ $T_j = 25\text{ }^\circ\text{C}$	-	5	-	nC

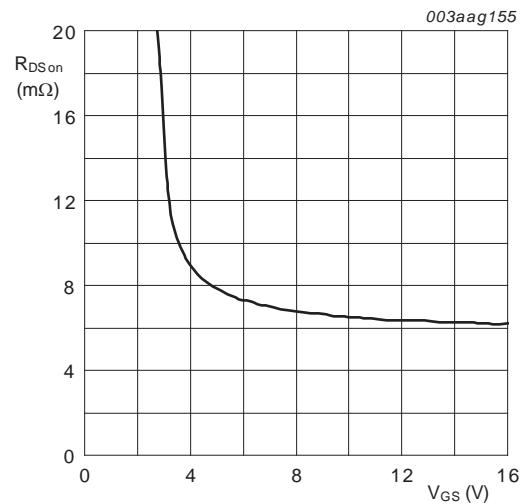
Source-drain diode

V_{SD}	source-drain voltage	$I_S = 15\text{ A}; V_{GS} = 0\text{ V}; T_j = 25\text{ }^\circ\text{C};$ see Figure 17	-	0.85	1.1	V
t_{rr}	reverse recovery time	$I_S = 15\text{ A}; di_S/dt = -100\text{ A}/\mu\text{s}; V_{GS} = 0\text{ V};$	-	21	-	ns
Q_r	recovered charge	$V_{DS} = 15\text{ V}$	-	13	-	nC
t_a	reverse recovery rise time	$V_{GS} = 0\text{ V}; I_S = 15\text{ A}; di_S/dt = -100\text{ A}/\mu\text{s};$ $V_{DS} = 15\text{ V};$ see Figure 18	-	12	-	ns
t_b	reverse recovery fall time		-	9	-	ns



$T_j = 25^\circ\text{C}$

Fig 6. Output characteristics; drain current as a function of drain-source voltage; typical values



$T_j = 25^\circ\text{C}; I_D = 15\text{ A}$

Fig 7. Drain-source on-state resistance as a function of gate-source voltage; typical values

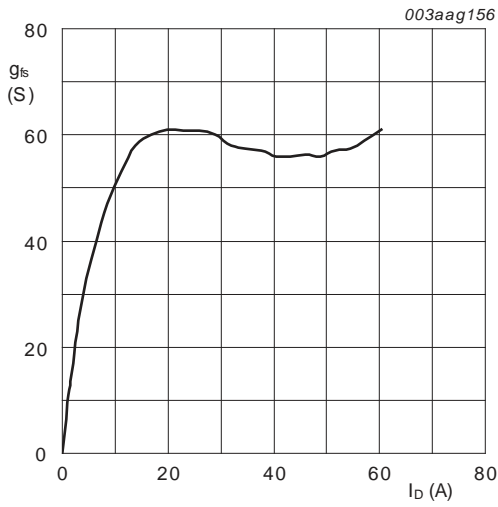


Fig 8. Forward transconductance as a function of drain current; typical values

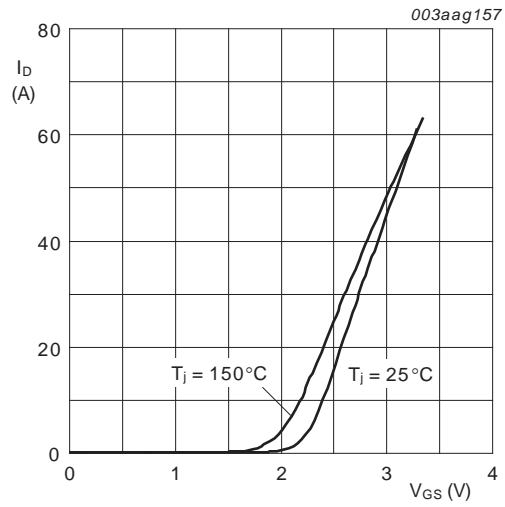


Fig 9. Transfer characteristics; drain current as a function of gate-source voltage; typical values

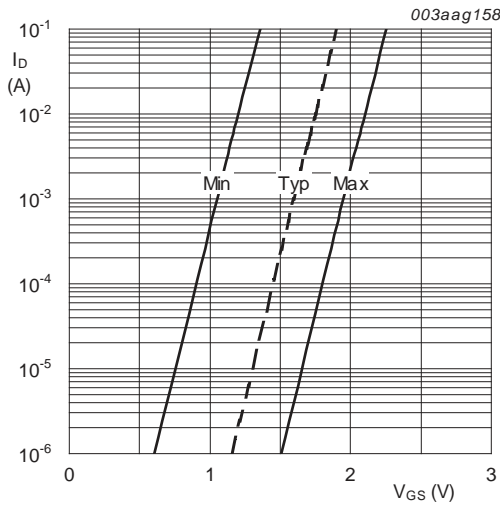


Fig 10. Sub-threshold drain current as a function of gate-source voltage

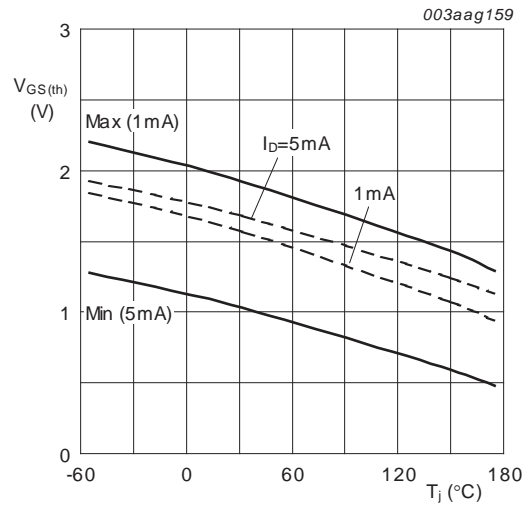
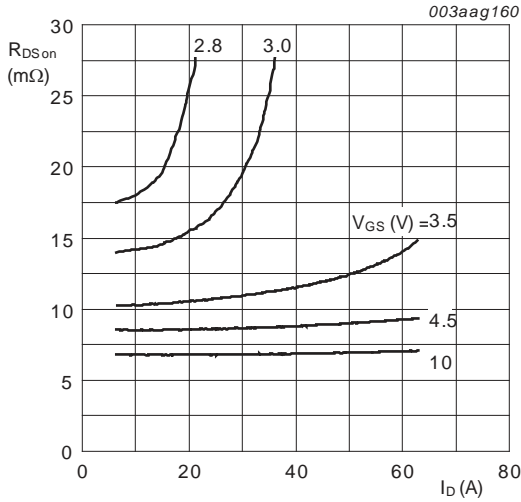
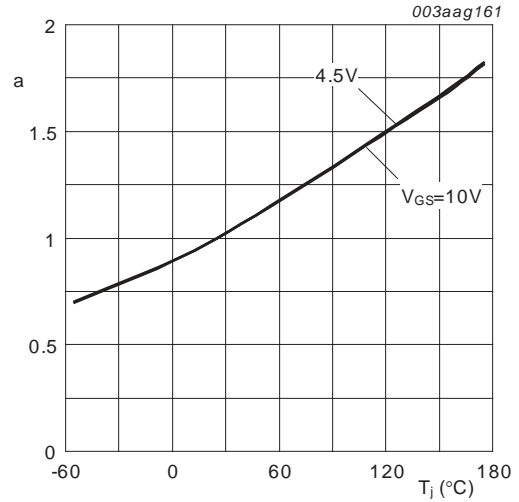


Fig 11. Gate-source threshold voltage as a function of junction temperature



$T_j = 25^\circ\text{C}$

Fig 12. Drain-source on-state resistance as a function of drain current; typical values



$$a = \frac{R_{DS(on)}}{R_{DS(on)(25^\circ\text{C})}}$$

Fig 13. Normalized drain-source on-state resistance factor as a function of junction temperature

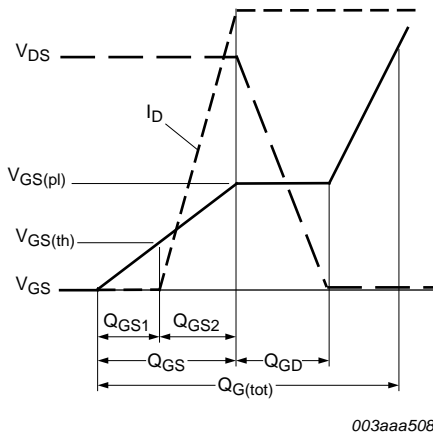
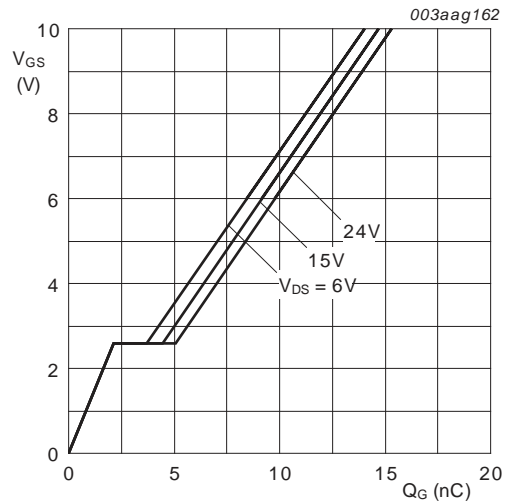
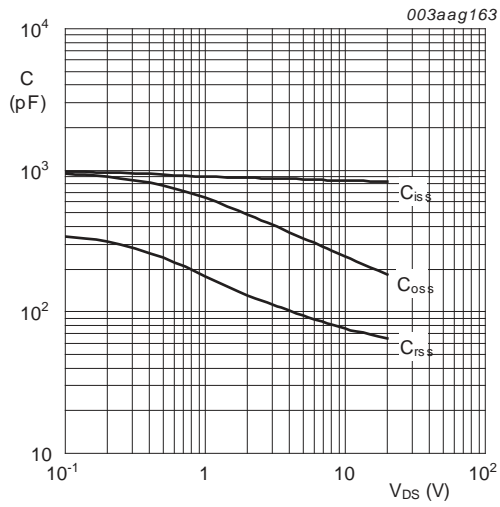


Fig 14. Gate charge waveform definitions



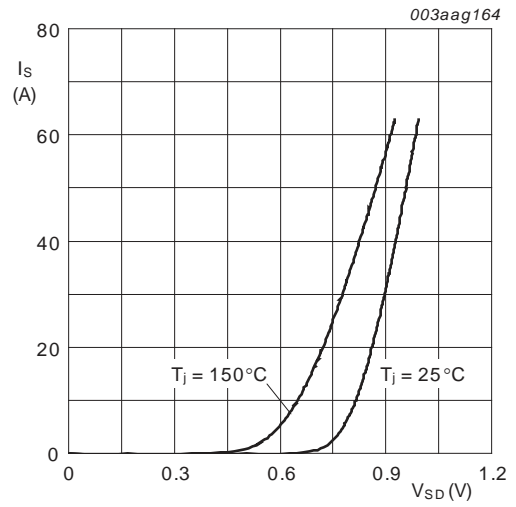
$T_j = 25^\circ\text{C}; I_D = 15\text{A}$

Fig 15. Gate-source voltage as a function of gate charge; typical values



$V_{GS} = 0V; f = 1MHz$

Fig 16. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values



$V_{GS} = 0V$

Fig 17. Source current as a function of source-drain voltage; typical values

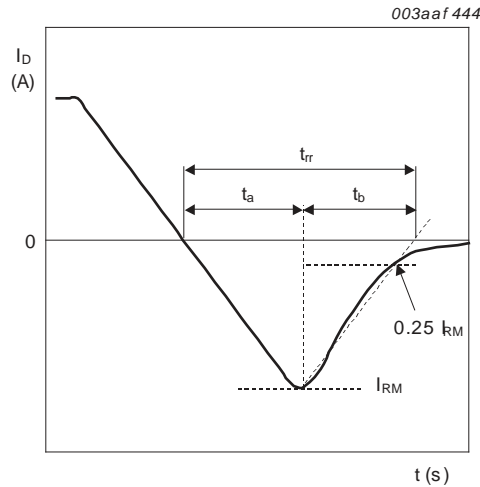


Fig 18. Reverse recovery timing definition

7. Package outline

Plastic single-ended surface-mounted package (LPAK; Power-SO8); 4 leads

SOT669

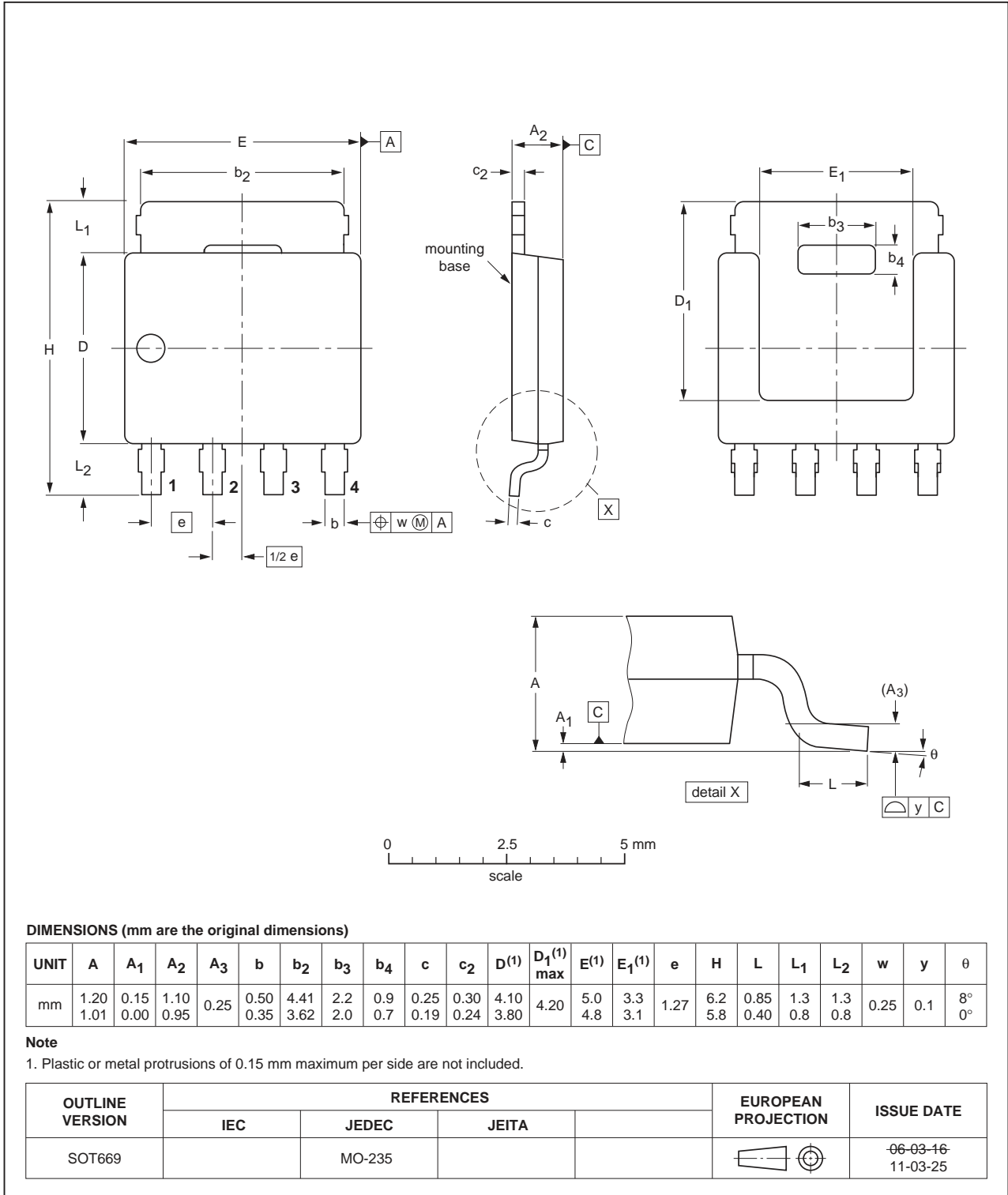


Fig 19. Package outline SOT669 (LPAK; Power-SO8)

8. Revision history

Table 7. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PSMN8R0-30YLC v.2	20110901	Product data sheet	-	PSMN8R0-30YLC v.1
Modifications:	• Data sheet status changed from objective to product.			
PSMN8R0-30YLC v.1	20110712	Objective data sheet	-	-

9. Legal information

9.1 Data sheet status

Document status ^[1] ^[2]	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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